

Features:

- n Low $V_{CE(sat)}$ IGBT
- n Low switching losses
- n 10us short circuit capability
- n Fast & soft reverse recovery FRD
- n Temperature sense included
- n Maximum junction temperature 175°C
- n Industry standard package with soldering pins for PCB mounting

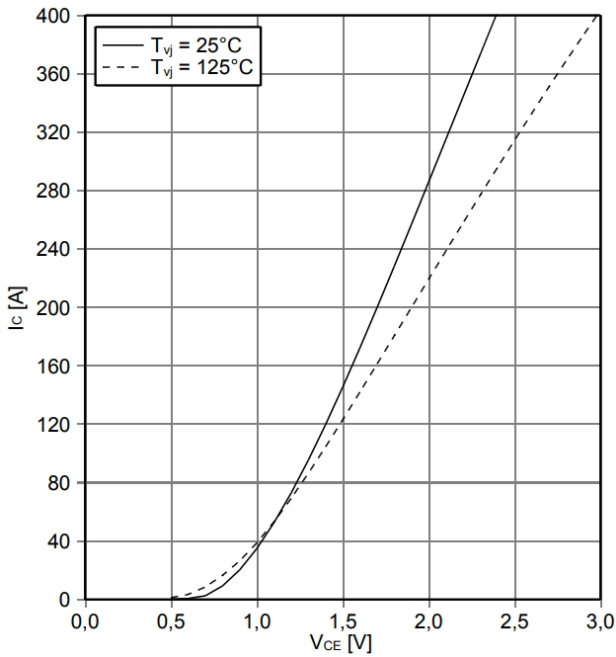
Typical Applications:

- n Inverter for Motor Drive
- n AC and DC servo drive amplifier
- n Uninterruptible Power Supply

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V_{CES}	Collector-Emitter voltage	$T_j=25^\circ\text{C}$			1200	V
V_{GES}	Gate-Emitter voltage	$T_j=25^\circ\text{C}$			± 20	V
I_C	Collector current	Continuous @ $T_C=100^\circ\text{C}$			200	A
I_{CP}		$T_j=25^\circ\text{C}, 1\text{ms}$			400	A
P_C	Collector power dissipation				1200	W
T_j	Junction temperature	/			150	$^\circ\text{C}$
T_{stg}	Storage temperature	/	-40		125	$^\circ\text{C}$
V_{iso}	Isolation between terminal and copper base	$T_j=25^\circ\text{C}, \text{AC: } 1\text{minute}$		2500		V
Screw torque	Mounting(M5)	/	3.0	4.0	5.0	N·m
I_{CES}	Zero gate voltage collector current	$T_j=25^\circ\text{C}, V_{CE}=1200\text{V}, V_{GE}=0\text{V}$			5.0	mA
I_{GES}	Gate-Emitter leakage current	$T_j=25^\circ\text{C}, V_{CE}=0\text{V}, V_{GE}=\pm 20\text{V}$			± 400	nA
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j=25^\circ\text{C}, V_{CE}=20\text{V}, I_C=1.7\text{mA}$	5.0	6.0	7.0	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^\circ\text{C}, V_{GE}=15\text{V}, I_C=200\text{A}$		2.00	2.50	V
		$T_j=125^\circ\text{C}, V_{GE}=15\text{V}, I_C=200\text{A}$		2.40		V
$R_{G(int)}$	Integrated Gate Resistor			6		Ω
C_{ies}	Input capacitance	$T_j=25^\circ\text{C}, V_{CE}=25\text{V}, V_{GE}=0\text{V}, f=1\text{MHz}$		18		nF
t_{on}	Turn-on time	$T_j=125^\circ\text{C}, V_{CC}=600\text{V}, I_C=200\text{A}, V_{GE}=\pm 15\text{V}, R_G=10\Omega, \text{Inductive load}$		85		ns
t_r				45		ns
t_{off}				400		ns
t_f	Turn-off time			130		ns
tsc	Short circuit withstand time	$T_j=150^\circ\text{C}, V_{CC}=720\text{V}, V_{GE}=\pm 15\text{V}, R_G=10\Omega$	10			μs
V_F	Forward on voltage	$T_j=25^\circ\text{C}, I_F=200\text{A}$		2.00	2.20	V
		$T_j=125^\circ\text{C}, I_F=200\text{A}$		2.00		V
t_{rr}	Reverse recovery time	$T_j=125^\circ\text{C}, I_F=200\text{A}$		350		ns
		$T_j=150^\circ\text{C}, I_F=200\text{A}$		260		ns
$R_{th(j-c)}$	Thermal resistance(1 device)	IGBT			0.08	$^\circ\text{C/W}$
		FWD			0.1	$^\circ\text{C/W}$
$R_{th(c-f)}$	Contact thermal resistance (1 device)	With thermal compound		0.050		$^\circ\text{C/W}$
W_t	Weight				350	g
Outline	454H3P					

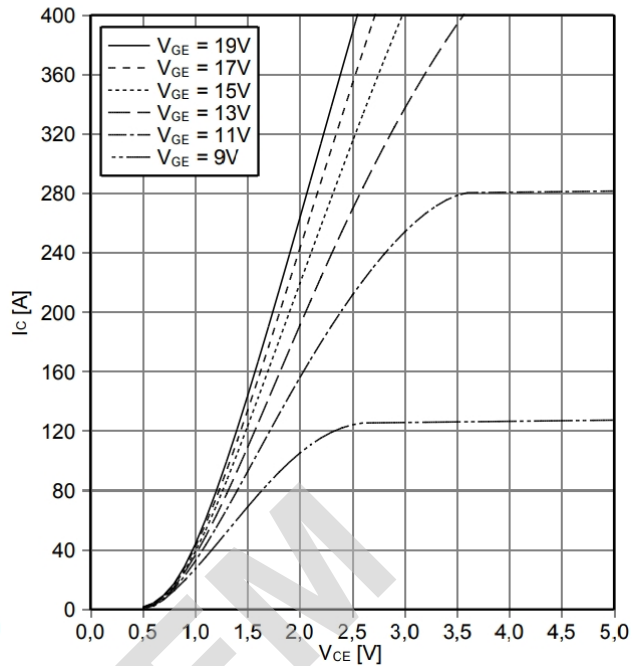
output characteristic IGBT,Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



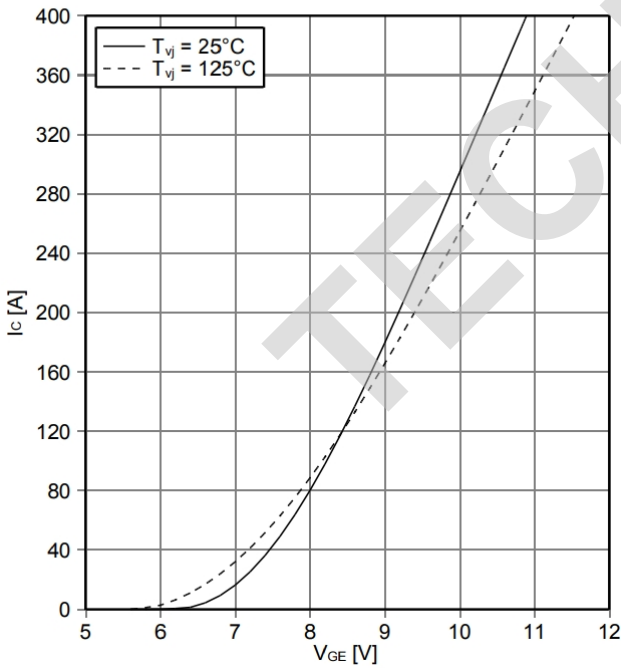
output characteristic IGBT,Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 125^\circ\text{C}$



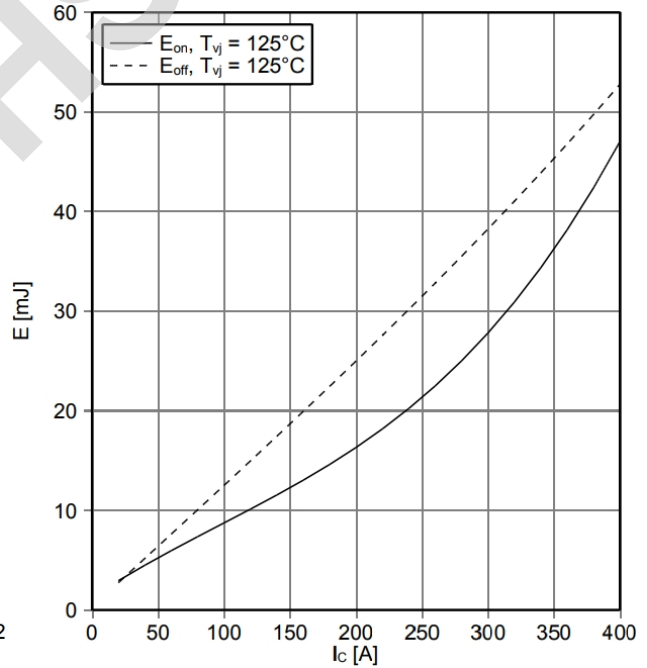
transfer characteristic IGBT,Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



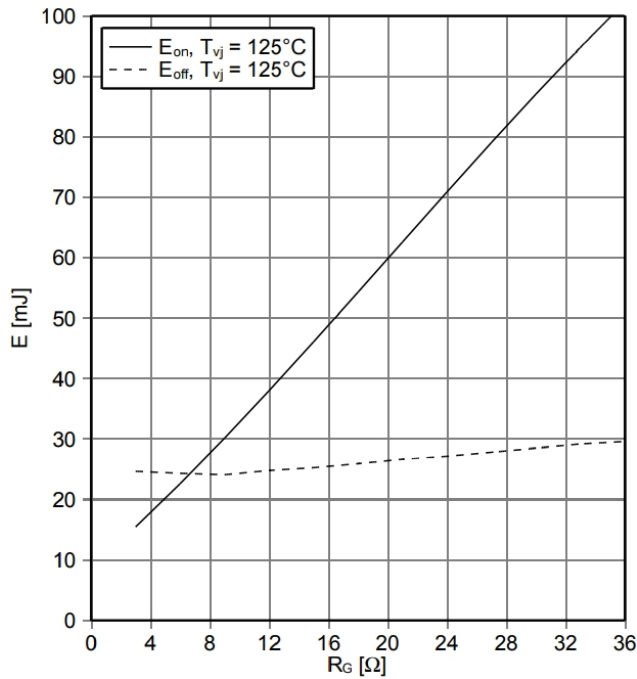
switching losses IGBT,Inverter (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 3.6\ \Omega, R_{Goff} = 3.6\ \Omega, V_{CE} = 600\text{ V}$



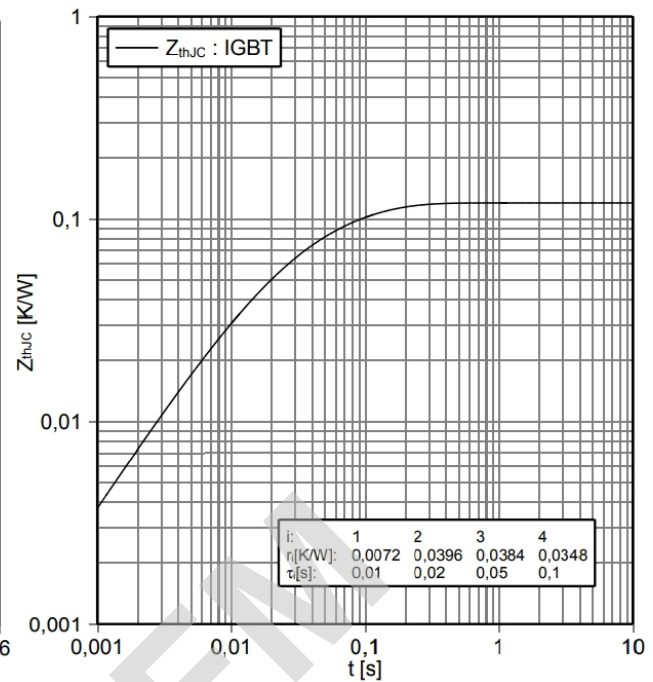
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$, $E_{off} = f(R_G)$
 $V_{GE} = \pm 15 V$, $I_C = 200 A$, $V_{CE} = 600 V$



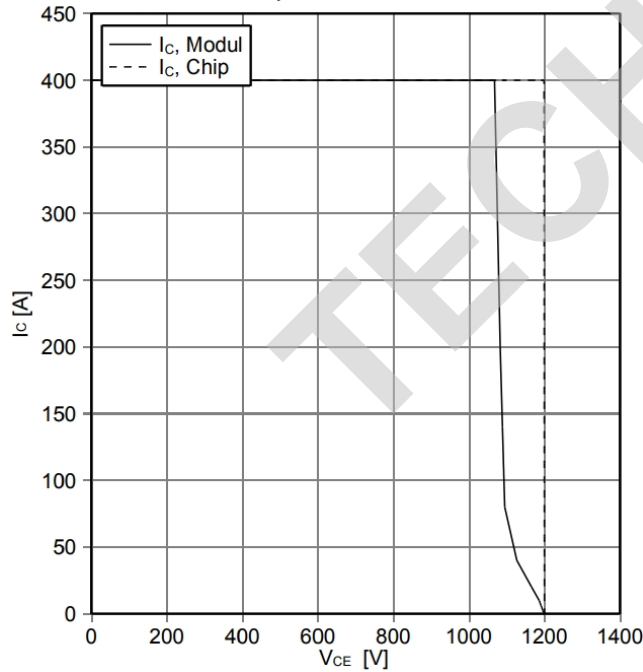
transient thermal impedance IGBT, Inverter

$Z_{thJC} = f(t)$



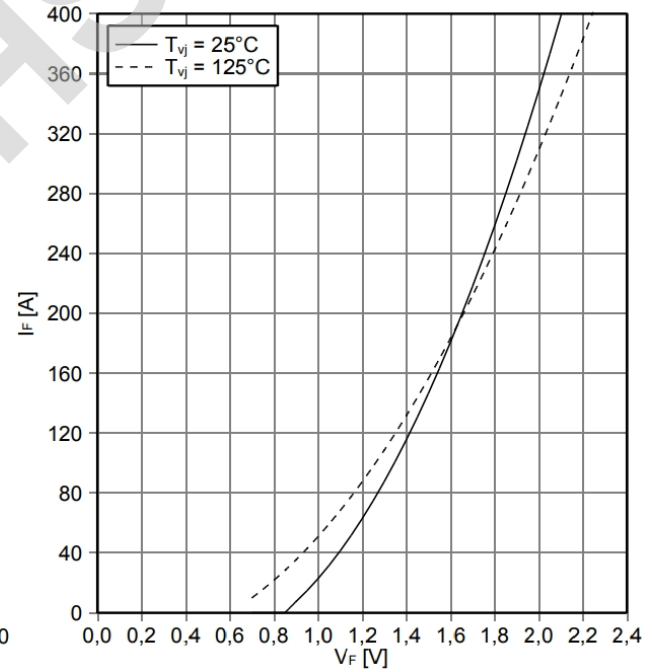
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 V$, $R_{Goff} = 3.6 \Omega$, $T_{vj} = 125^\circ C$



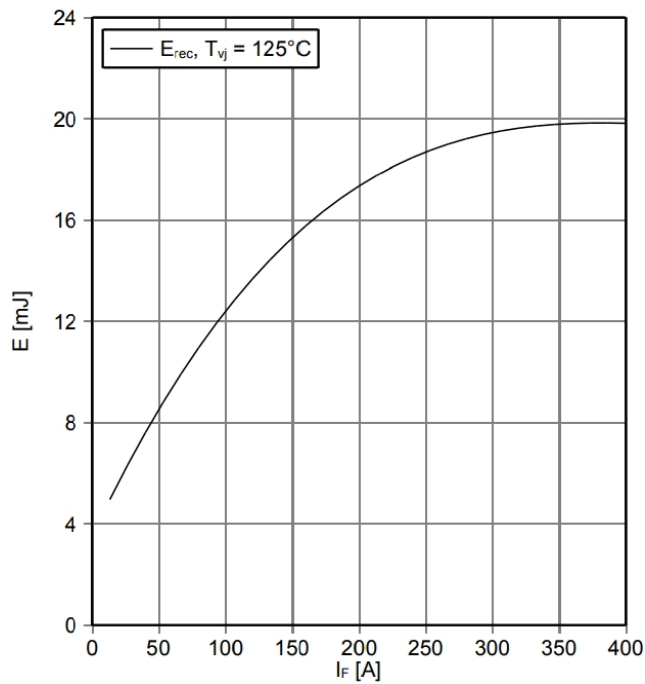
forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



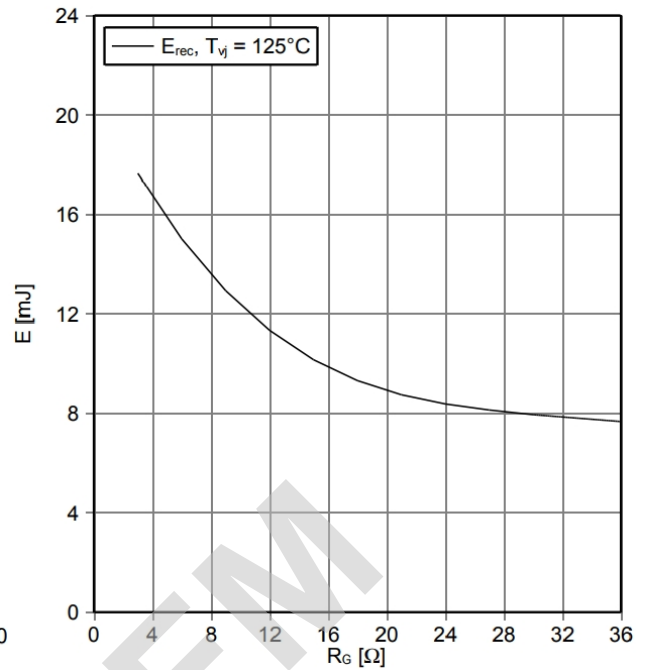
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 3.6 \Omega, V_{CE} = 600 V$



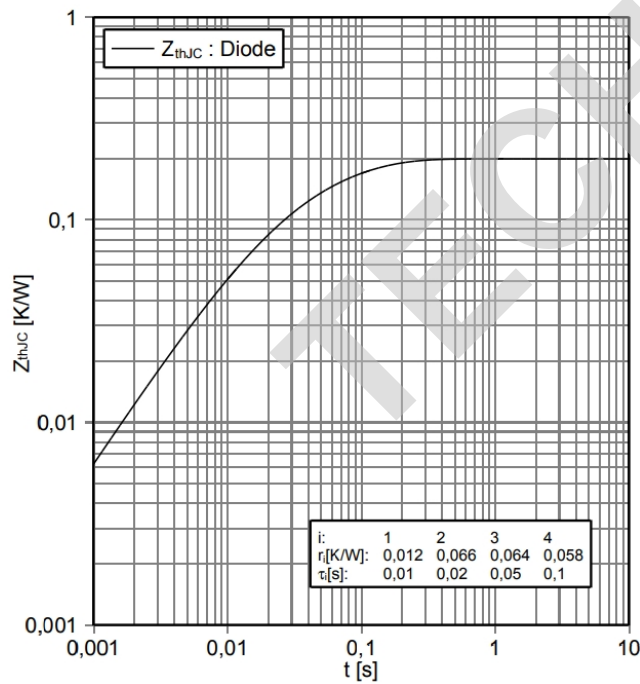
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 200 A, V_{CE} = 600 V$



transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



i:	1	2	3	4
r _i [K/W]:	0,012	0,066	0,064	0,058
τ _i [s]:	0,01	0,02	0,05	0,1

Outline:

